Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0407-02** DATE: 7/26/2004
Product Affected: IDTCV123

Date Effective: 10/26/2004

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ■ Date Code "EY" prefix
- ☐ Other

Contact: Bimla Paul
Title: Quality Assurance Manager
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Attachment: ■ Yes ☐ No

Samples: Available on request

DESCRIPTION AND PURPOSE OF CHANGE:
- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

This notification is to advise customers that IDT has qualified an alternate Wafer Fabrication facility - IDT Fab 4 (Hillsboro, Oregon) for IDTCV123. Please see attachment for qualification data and additional details.

RELIABILITY/QUALIFICATION SUMMARY: Please see attached qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ☐ ***Approval for shipments prior to effective date.***

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

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ATTACHMENT - PCN #: L0407-02

PCN Type: Manufacturing site - Wafer Fab Facility

Datasheet Change: No

Detail of Change: This notification is to advise customers that IDT has qualified an alternate Wafer Fabrication facility - IDT Fab-4 (Hillsboro, Oregon) for IDTCV123. The addition of IDT Fab-4 facility will increase manufacturing capacity and improve the support of current and future production needs.

Wafer Fab Facility	Date Code Prefix
Vanguard	BZ
IDT Fab-4 (Alternate Fab)	EY

Qualification Data:

Qualification Plan #: QLG-04-04 **Test Vehicle:** IDTCV125 / IDTCV110L

Test Description/Condition	Test Methods	SS/# Fails	Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45 / 0	45 / 0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45 / 0	45 / 0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45 / 0	45 / 0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	154 / 0	154 / 0
ESD Human Body Model (3000V)	MIL-STD-883, Method 3015	3 / 0	3 / 0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	6 / 0	6 / 0